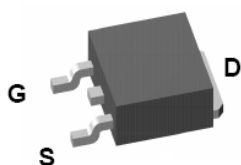


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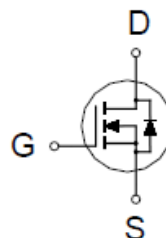
N-Channel Enhancement Mode MOSFET

PRODUCT SUMMARY

$V_{(BR)DSS}$	$R_{DS(ON)}$	I_D
150V	60m Ω @ $V_{GS} = 10V$	20A



TO-252



ABSOLUTE MAXIMUM RATINGS ($T_A = 25\text{ }^{\circ}\text{C}$ Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS		SYMBOL	LIMITS	UNITS
Gate-Source Voltage		V_{GS}	± 12	V
Continuous Drain Current	$T_C = 25\text{ }^{\circ}\text{C}$	I_D	20	A
	$T_C = 100\text{ }^{\circ}\text{C}$		15	
Pulsed Drain Current ¹		I_{DM}	60	
Avalanche Current		I_{AS}	20	mJ
Avalanche Energy	$L = 0.47\text{mH}$	E_{AS}	94	
Repetitive Avalanche Energy ²	$L = 0.47\text{mH}$	E_{AR}	35	
Power Dissipation	$T_C = 25\text{ }^{\circ}\text{C}$	P_D	48	W
	$T_C = 100\text{ }^{\circ}\text{C}$		20	
Operating Junction & Storage Temperature Range		T_J, T_{STG}	-55 to 150	$^{\circ}\text{C}$
Lead Temperature (¹ / ₁₆ " from case for 10 sec.)		T_L	275	

THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNITS
Junction-to-Case	$R_{\theta JC}$		2.6	$^{\circ}\text{C} / \text{W}$
Junction-to-Ambient	$R_{\theta JA}$		62.5	

¹Pulse width limited by maximum junction temperature.

²Duty cycle $\leq 1\%$.

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PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNITS
			MIN	TYP	MAX	
STATIC						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = 250μA	150			V
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250μA	0.45	0.75	1.20	
Gate-Body Leakage	I _{GSS}	V _{DS} = 0V, V _{GS} = ±12V			±100	nA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 120V, V _{GS} = 0V			1	μA
		V _{DS} = 100V, V _{GS} = 0V , T _J = 125 °C			10	
On-State Drain Current ¹	I _{D(ON)}	V _{DS} = 5V, V _{GS} = 5V	60			A
Drain-Source On-State Resistance ¹	R _{DS(ON)}	V _{GS} = 3V, I _D = 3A		62	80	mΩ
		V _{GS} = 5V, I _D = 10A		56	70	
		V _{GS} = 10V, I _D = 15A		50	60	
Forward Transconductance ¹	g _{fs}	V _{DS} = 5V, I _D = 10A		26		S
DYNAMIC						
Input Capacitance	C _{iss}	V _{GS} = 0V, V _{DS} = 25V, f = 1MHz		7660		pF
Output Capacitance	C _{oss}			725		
Reverse Transfer Capacitance	C _{rss}			420		
Total Gate Charge ²	Q _g	V _{DS} = 0.5V _{(BR)DSS} , V _{GS} = 4.5V, I _D = 10A		107	140	nC
Gate-Source Charge ²	Q _{gs}			18		
Gate-Drain Charge ²	Q _{gd}			60		
Turn-On Delay Time ²	t _{d(on)}	V _{DS} = 75V, I _D ≅ 10A, V _{GS} = 10V, R _{GS} = 16Ω		18		nS
Rise Time ²	t _r			115		
Turn-Off Delay Time ²	t _{d(off)}			338		
Fall Time ²	t _f			384		
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS (T _J = 25 °C)						
Continuous Current	I _S				20	A
Pulsed Current ³	I _{SM}				60	
Forward Voltage ¹	V _{SD}	I _F = I _S , V _{GS} = 0V			1.3	V
Reverse Recovery Time	t _{rr}	I _F = I _S , dI _F /dt = 100A / μS		57		nS
Peak Reverse Recovery Current	I _{RM(REC)}			60		A
Reverse Recovery Charge	Q _{rr}			0.13		μC

¹Pulse test : Pulse Width $\leq 300 \mu sec$, Duty Cycle $\leq 2\%$.

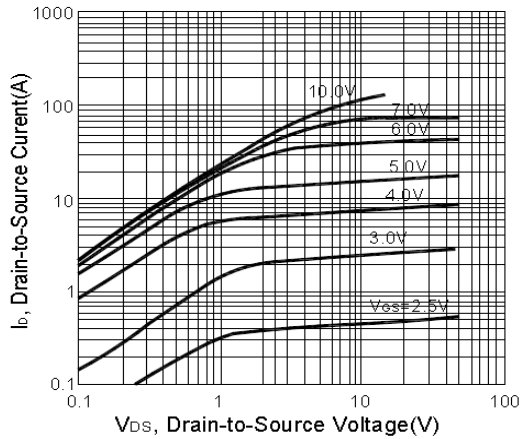
²Independent of operating temperature.

³Pulse width limited by maximum junction temperature.

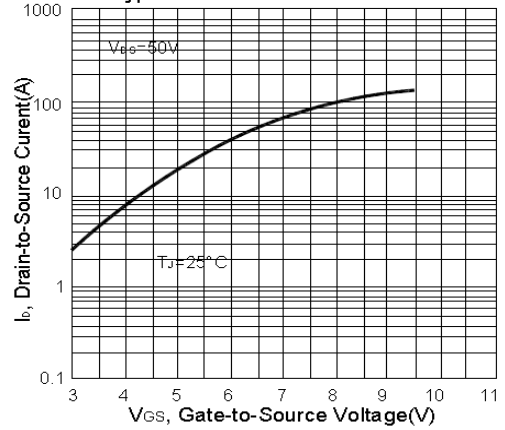
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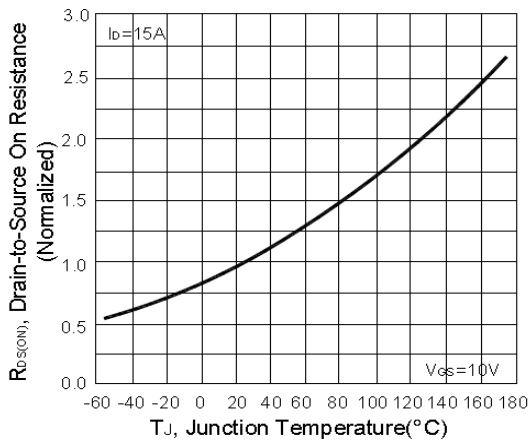
Typical Output Characteristics



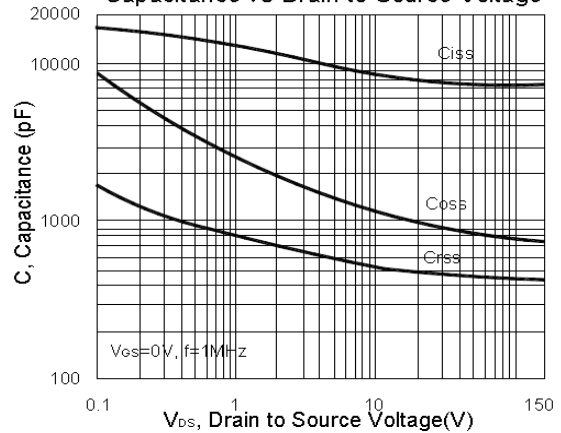
Typical Transfer Characteristics



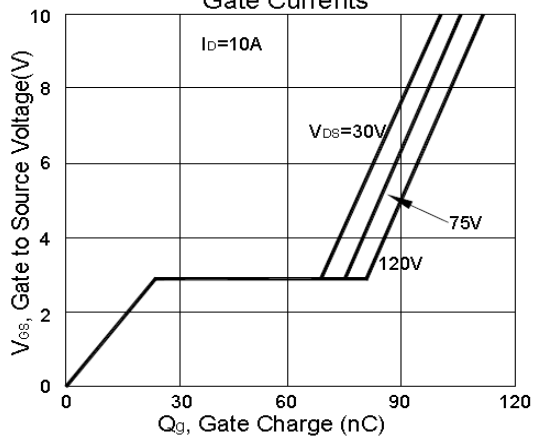
Normalized On-Resistance Vs. Temperature



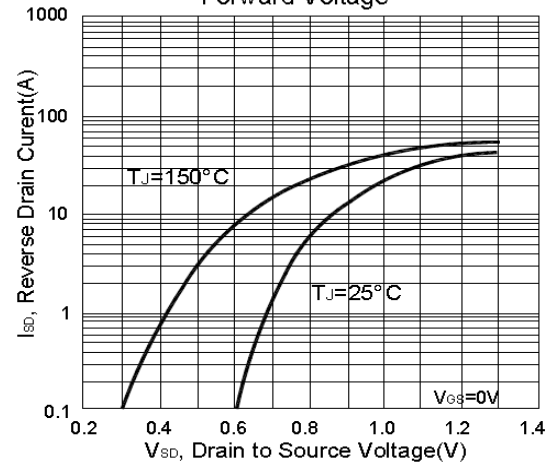
Capacitance vs Drain to Source Voltage



Gate Charge Waveforms for Constant Gate Currents

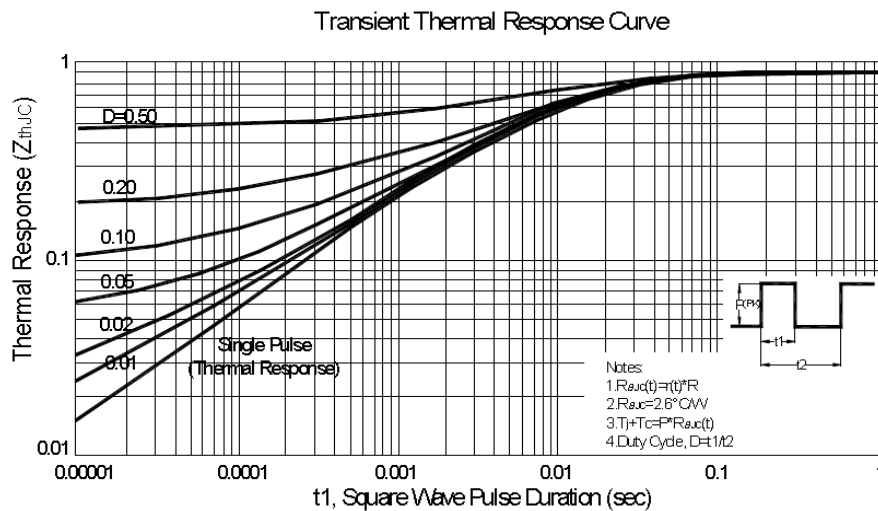
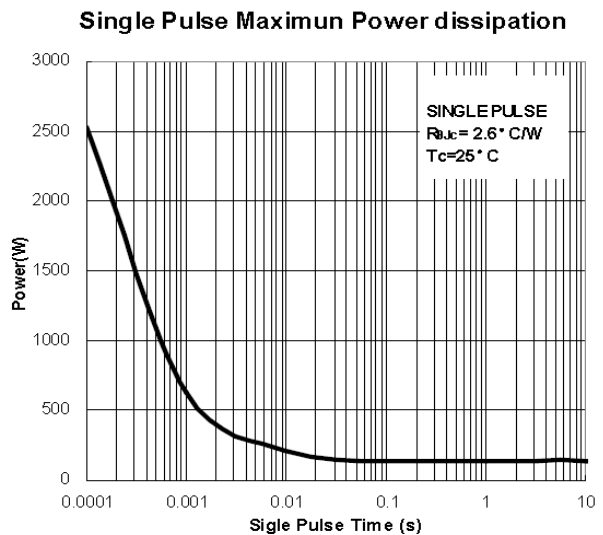
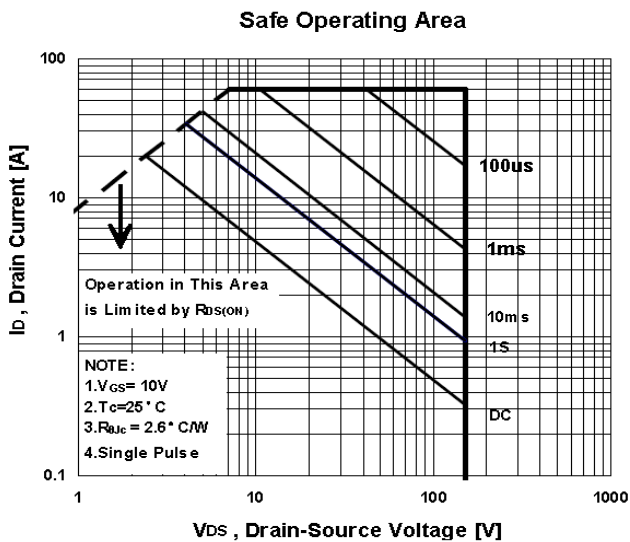
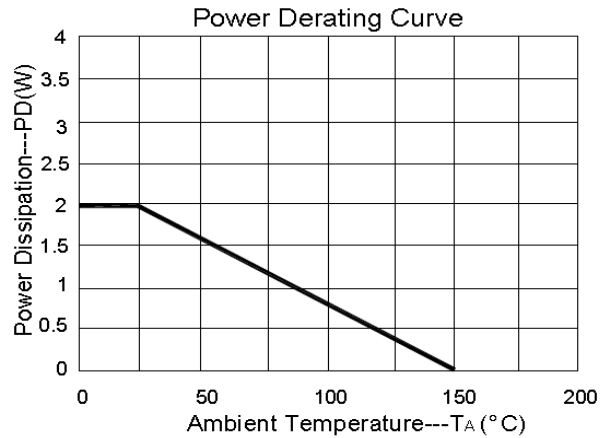
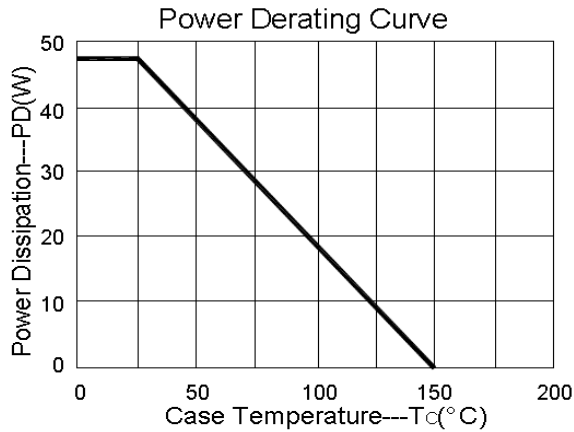


Typical Source-Drain Diode Forward Voltage



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Package Dimension

TO-252 (DPAK) MECHANICAL DATA

Dimension	mm			Dimension	mm		
	Min.	Typ.	Max.		Min.	Typ.	Max.
A	8.9	10	10.41	J	4.8		5.64
B	2.1	2.2	2.5	K	0.15		1.49
C	0.4	0.5	0.61	L	0.4	0.76	0.91
D	0.82	1.2	1.5	M	4.2	4.58	5
E	0.35	0.5	0.65	S	4.57	5.1	5.52
F	0		0.2	T	3.81	4.75	5.24
G	5.3	6.1	6.3	U	1.4		1.78
H	0.5		1.7	V	0.55	1.25	1.7
I	6.3	6.5	6.8				

